Tailoring Fe-Ni Based Alloys for Intermediate Temperature SOFC Interconnect Application⁺

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J. H. Zhu, S. J. Geng, D. A. Ballard and Z.G. Lu

Department of Mechanical Engineering

Tennessee Technological University (TTU), Cookeville, TN

M. P. Brady and I.G. Wright

Metals and Ceramics Division
Oak Ridge National Laboratory (ORNL), Oak Ridge, TN

X.D. Zhou and H. Anderson

Electronic Materials Applied Research Center University of Missouri-Rolla (UMR), Rolla, MO

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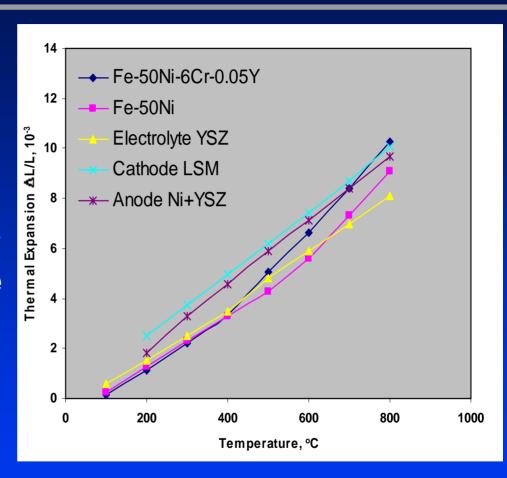
Why Cr-free or low Cr alloys as SOFC interconnect material?

- Currently, the metallic interconnects for intermediatetemperature SOFC are the Cr₂O₃-forming alloys such as Ebrite, Crofer, and Haynes 230 due to the electrically conductive nature of Cr₂O₃ compared to Al₂O₃ and SiO₂.
- However, an inherent weakness of Cr₂O₃-forming alloys is the formation of volatile Cr species due to chromium evaporation, which will migrate to and thus poison the cathode, resulting in SOFC performance degradation
- Two approaches can be taken to address this issue:
 - ✓ Surface coating approach
 - ✓ Alloy design approach

Cr-free or low Cr Fe-Ni alloys specifically tailored for SOFC interconnect application might completely resolve the Cr poisoning issue in SOFC stacks.

Cr-free or low-Cr Fe-Ni based alloys are potential interconnect materials for SOFC

- Fe-Ni alloys with about 50 wt. %Ni exhibit thermal expansion behavior close to that of other cell components
- Fe-Ni alloys are Cr-free or low Cr, which is desirable to eliminate the Cr poisoning problem.
- The oxidation resistance and scale conductivity of the Fe-Ni based alloys might be tailored via alloy design



Thermal Expansion vs. Temperature for the Fe-50Ni and Fe-50Ni-6Cr-0.05Y Alloys (wt.%), as Compared to Other Cell Components

Alloy Design of New Fe-Ni Base Alloys Forming Double-Layer Oxide Structure During Oxidation

CTE Match with Other Cell Components

Alloying additions such as Fe, Co, Ni, Mo, Nb, Ti, Cr, etc. will be controlled to maintain the CTE values of the new Fe-Ni based alloys at the desired level.

Oxide Scale Conductivity

In addition to control the Fe-Ni ratio, other transition metals will be identified and added to increase the electrical conductivity of the NiFe₂O₄ spinel layer.

Oxidation Resistance

An inner layer of dense, protective, and electrically conductive oxide (e.g. NiO, Cr₂O₃) will be formed after oxidation.

Cr-free Outer Layer: NiFe₂O₄

Inner Layer: Protective Oxides

Substrate: Fe-Ni Alloy

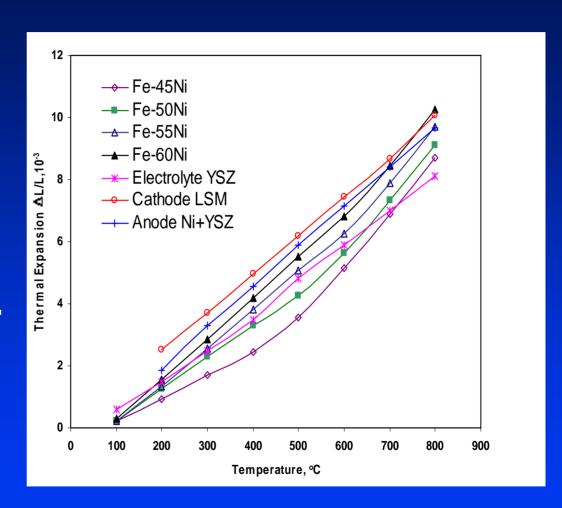
Schematic of the Desirable Double-Layer Oxide Structure

Binary Fe-Ni Alloys: Identifying the Critical Issues

Low-Cr Fe-Ni Alloy Development: Approach to Form the Desired Double-Layer Oxide Structure

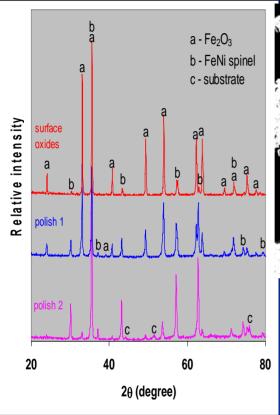
CTE of Cr-free Fe-Ni Binary Alloys

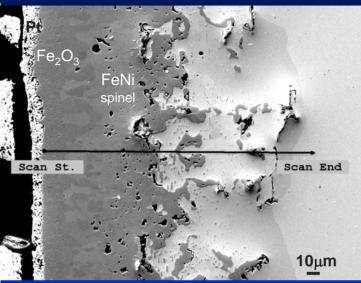
- The coefficient of thermal expansion (CTE) of binary Fe-Ni alloys with different Ni level (45-60wt.%) increased with the increase of Ni content.
- expansion behavior of the Fe-Ni alloys was close to that of other cell components.



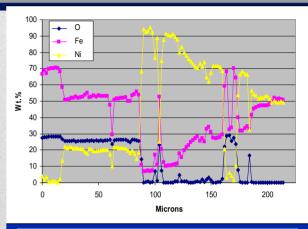
Thermal Expansion vs. Temperature for the Fe-Ni Alloys with Different Ni Content (wt.%), as Compared to Other Cell Components

EPMA was used to determine the spinel composition formed on the binary Fe-Ni alloys





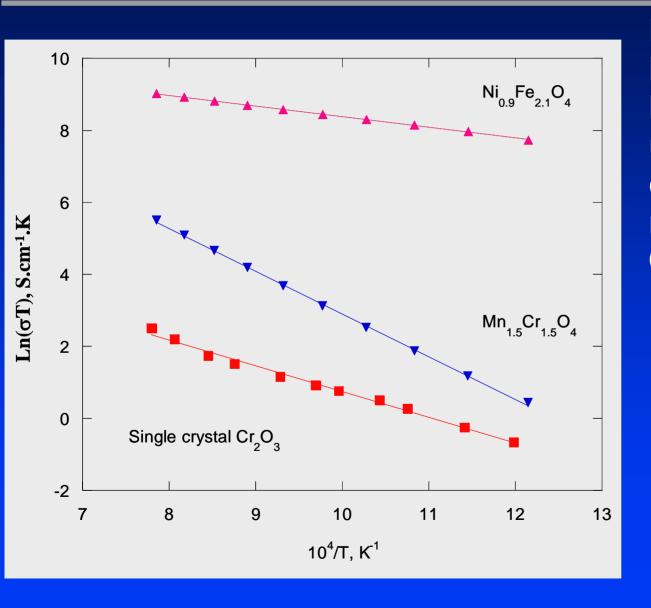
XRD patterns, cross-section, and electron-probe micro-analysis (EPMA) results of Fe-50Ni-0.05Y after oxidation for 500h in air at 800°C



Microns	At.%:	0	Fe	Ni
46		55.4	33.2	11.4
48		56.0	32.6	11.4
50		55.1	33.2	11.7
52		55.6	32.8	11.6
54		55.4	32.7	11.9
56		55.4	32.7	11.9
58		55.7	32.6	11.7

- The surface oxide layer contained Fe₂O₃, which was in contact with a Ni_{1-x}Fe_{2+x}O₄ spinel layer.
- **■** EPMA results indicated that the composition of the spinel was close to Ni_{0.9}Fe_{2.1}O₄.

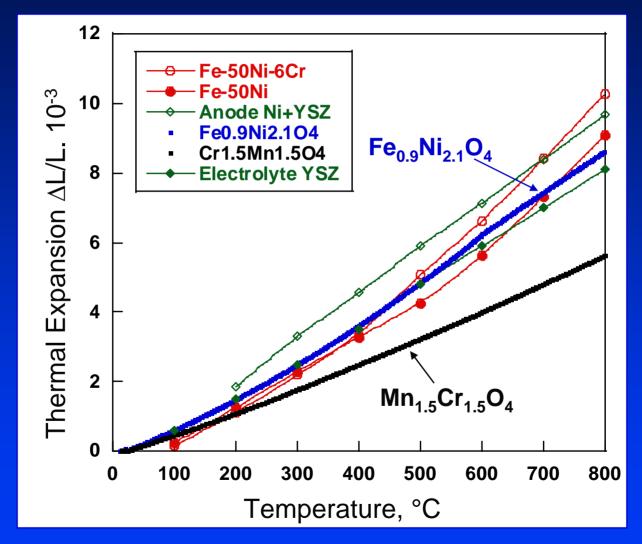
Ni_{0.9}Fe_{2.1}O₄ possessed much higher electrical conductivity than Mn_{1.5}Cr_{1.5}O₄ or Cr₂O₃



Dense pellets of Ni_{0.9}Fe_{2.1}O₄ and Mn_{1.5}Cr_{1.5}O₄ were used for electrical conductivity measurement (4-point DC technique):

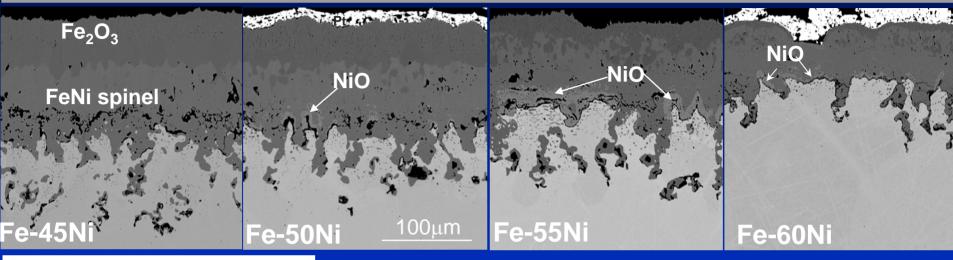
- ✓ Ni_{0.9}Fe_{2.1}O₄ similar to the spinel formed on Fe-Ni alloys
- ✓ Mn_{1.5}Cr_{1.5}O₄ similar to the spinel formed on Crofer (Fe-Cr-Mn)

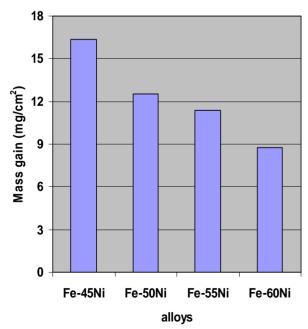
Excellent Match in Thermal Expansion of Fe_{0.9}Ni_{2.1}O₄ with the Fe-Ni alloys



The (Fe,Ni)₃O₄ spinel layer formed on the Fe-Ni alloys is expected to resist cracking during thermal cycling

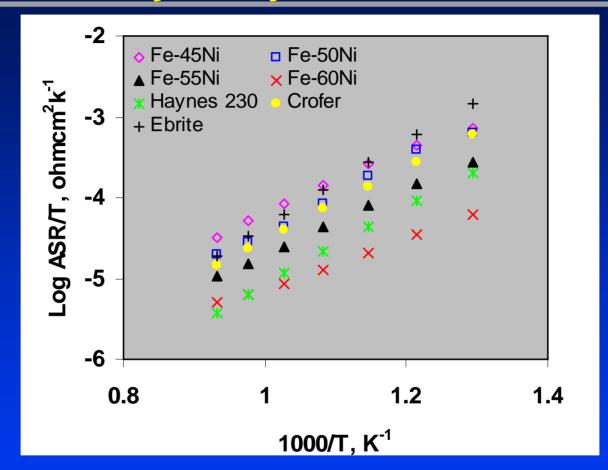
Effect of Ni Content on Oxidation Resistance of the Fe-Ni Binary Alloys in Air 800°C-500h





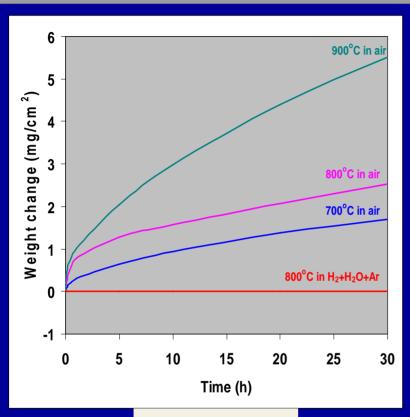
- The mass gain of Fe-Ni alloys decreased with the increase of Ni content in the alloys.
- The oxides scale became thinner with the increase in Ni content.
- The thickness of the surface Fe₂O₃ layer decreased with the increase of Ni content.
- No NiO was formed on Fe-45Ni, while NiO was formed between the spinel and substrate on Fe-50Ni, Fe-55Ni and Fe-60Ni. The continuity of the NiO layer on Fe-55Ni and Fe-60Ni was better than on Fe-50Ni.

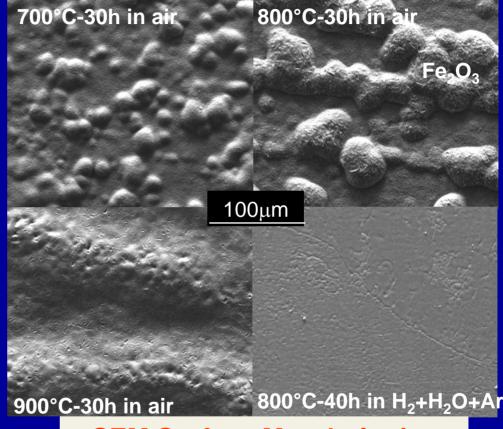
Comparison of ASR of the Oxide Scale on Fe-Ni Binary Alloys with Other Alloys



- The ASR of the oxide scale formed on the Fe-Ni alloys after oxidation at 800°C for 500h in air decreased with the increase of Ni content.
- The ASR of the oxide scale formed on the Fe-Ni alloys was comparable to that formed on Ebrite, Crofer and Haynes 230.

Effect of Temperature and Atmosphere on Oxidation Behavior of Fe-50Ni-0.05Y





TGA Data

SEM Surface Morphologies

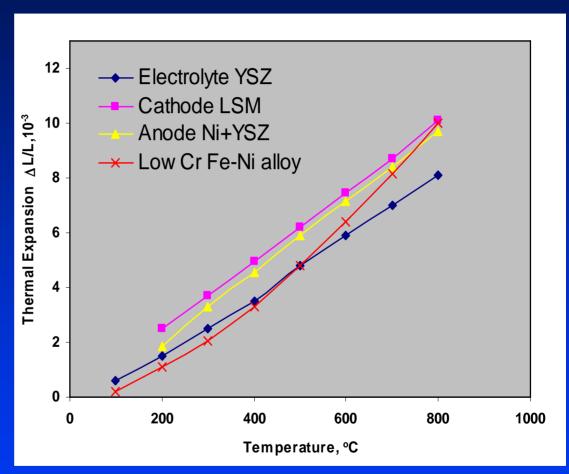
- The mass gain in the cathode environment (air) increased with the increase of oxidation temperature. The surface oxide nodules increased in size with the increase in oxidation temperature.
- No weight change was noticed in anode environment (Ar+H₂+H₂O).

Binary Fe-Ni Alloys: Identifying the Critical Issues

Low-Cr Fe-Ni Alloy Development: Approach to Form the Desired Double-Layer Oxide Structure

CTE of the New Low Cr Fe-Ni Based Alloy+

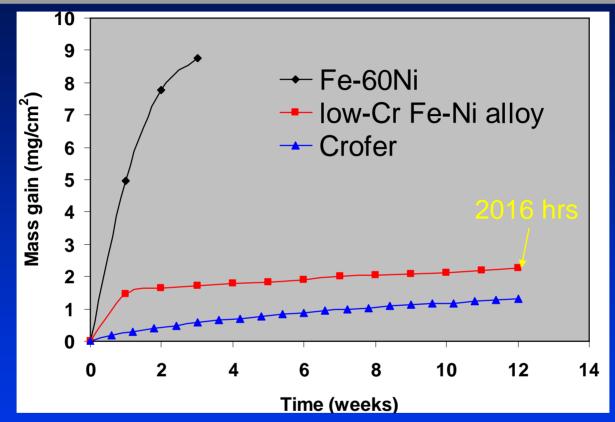
- The formation of continuous, modified Cr₂O₃ inner-layer underneath the spinel out-layer is proposed to enhance the oxidation resistance of the Fe-Ni alloys.
- The CTE of the Fe-Ni alloys increases as Cr content increases.
- The thermal expansion behavior of the new low Cr (6wt.%) Fe-Ni based alloy was close to that of other cell components



Thermal Expansion vs. Temperature for the low Cr Fe-Ni Alloy, as Compared to Other Cell Components

*The exact alloy composition - proprietary information

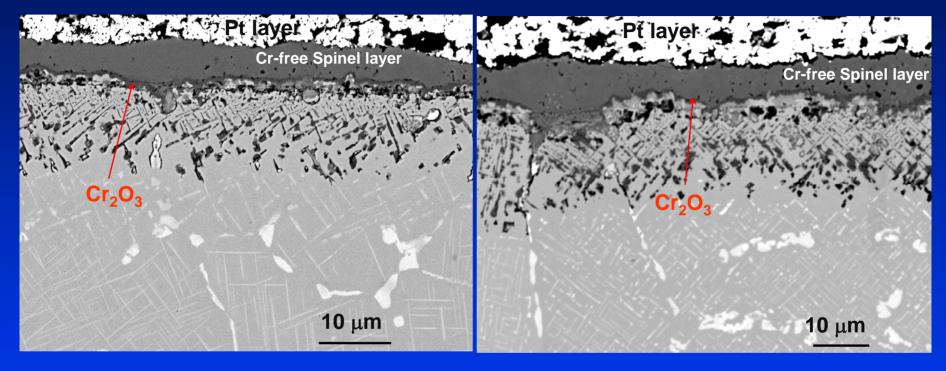
Isothermal Oxidation Kinetics of the Low-Cr Fe-Ni Based Alloy in Air at 800°C



- The newly-developed low-Cr Fe-Ni alloy showed significantly improved oxidation resistance compared to the binary Fe-Ni alloys
- After the 1st-week exposure, the oxidation rate of the new alloy was similar to that of Crofer.
- Large weight gain in the 1st week for the low-Cr Fe-Ni alloy was due to the *in-situ* formation of a Cr-free spinel layer.

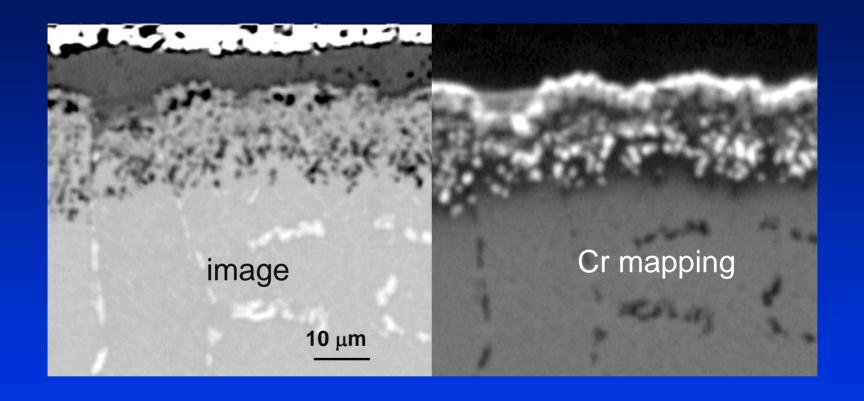
Cross-Sections of the Low-Cr Fe-Ni Based Alloy after Oxidation at 800°C in Air

3 weeks 12 weeks



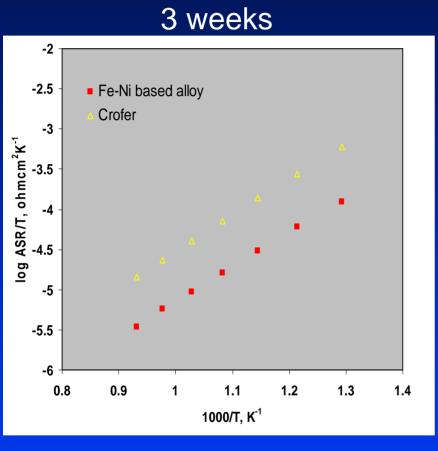
- The oxide scale formed on this alloy consisted of Cr-free spinel outer layer and chromia inner layer
- An internal oxidation zone with mainly Cr₂O₃ was observed underneath the chromia inner layer

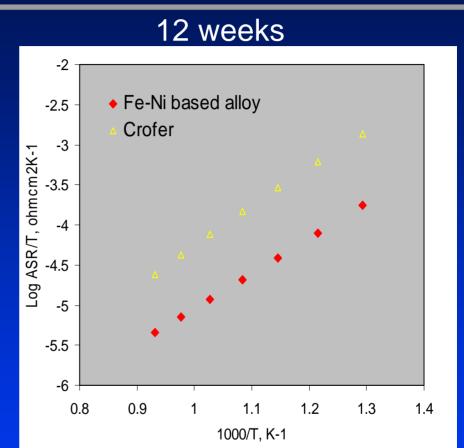
EPMA Result of the Low-Cr Fe-Ni Alloy after Oxidation for 12 weeks at 800°C in Air



- The spinel outer layer was essentially Cr-free
- The Cr₂O₃ inner layer is continuous

ASR of the Oxide Scale Formed on the Low Cr Fe-Ni Based Alloy after Oxidation at 800°C in Air

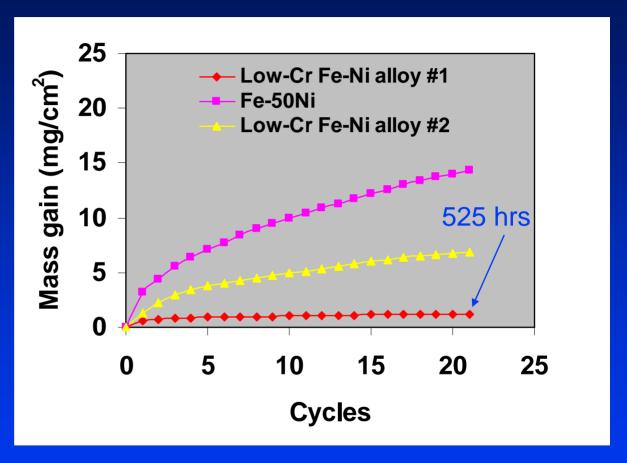




- The ASR of the oxide scale on the low-Cr Fe-Ni alloy after oxidation for 12 weeks was almost the same as that for 3 weeks
- The ASR of the oxide scale on Fe-Ni based alloy was lower than that on Crofer

Cyclic Oxidation of Low-Cr Fe-Ni Based Alloys at 800°C in Air

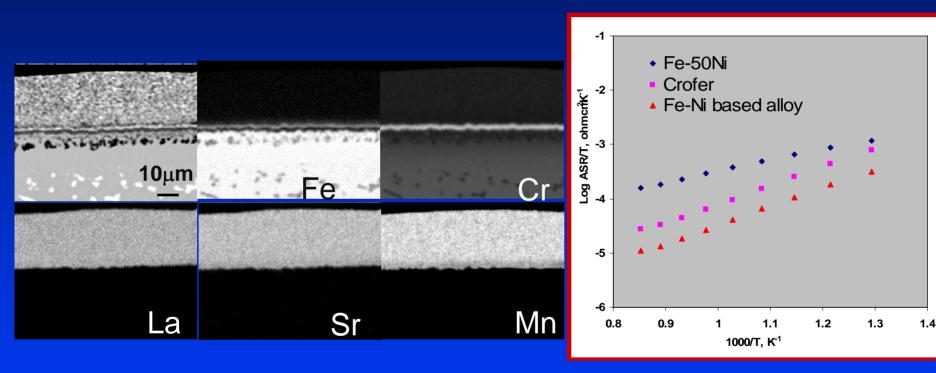
Each cycle consisted of holding at 800°C for 25 hours in air, followed by cooling to room temperature in air



- The mass gain of the optimized low-Cr Fe-Ni based alloy (#1) increased slightly with cycling after the first cycle
- No spallation was observed for all the alloys, consistent with the CTE data

Compatibility of the New Alloy with Cathode (LSM)

The alloy/cathode couples were oxidized for 300 hours at 900°C in air



Cross-section of the low Cr Fe-Ni based alloy with LSM

ASR of the low Cr Fe-Ni based alloy coated LSM

- Negligible interaction between the oxide scale and LSM
- Lower ASR for the low-Cr Fe-Ni alloy than that for Crofer

Summary

■ CTE (√)

The CTE of the binary and low Cr Fe-Ni alloys is close to that of other cell components.

■ ASR (√)

The ASR of the oxide scales formed on these new alloys is comparable to that of current SOFC interconnect alloys.

■ Oxidation Resistance (√)

While the oxidation resistance of the binary Fe-Ni alloys is not satisfactory, effective alloying additions have been identified to overcome this problem.

A series of new low-Cr Fe-Ni alloys have been developed that form an electrically conductive, Cr-free spinel outer layer atop an Cr_2O_3 inner layer during thermal oxidation.

Current/Future Work

- Current Work: On-going Phase I Study
 - Alloy Modification to Improve Oxidation Resistance and CTE
 - Oxidation Tests in Simulated Anode Environment as well as in Air with Different Water Vapor Levels
 - In-depth Study of Electrical Conduction Mechanism in NiFe₂O₄ spinel
 - Detailed Study of Alloy/Cathode Interaction/Compatibility
 - Cr Volatility Measurement at PNNL
- Future Work: Proposed Phase II Study
 - Further Optimization of Alloy Compositions
 - Scale-up of Alloy Production (in Collaboration with Some Commercial Alloy Producers)
 - Cell/Stack Testing with the New Interconnect Alloy (Inhouse, National Laboratories, SECA Industrial Teams)
 - Evaluation of Other Properties (Forming, Tensile, Creep, etc.)

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